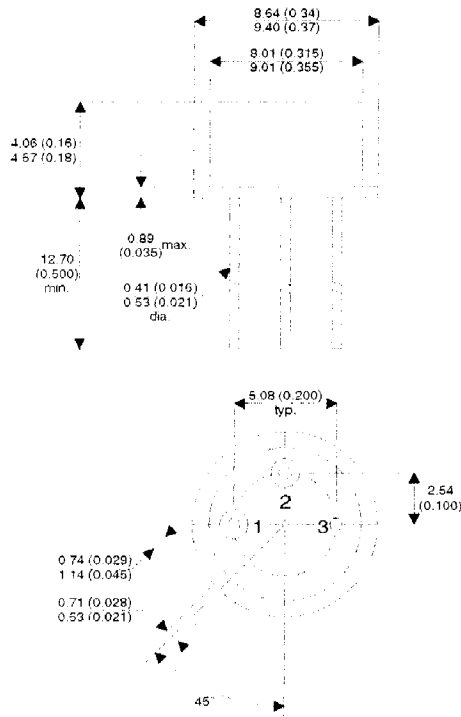


MECHANICAL DATA

Dimensions in mm (inches)



**P-CHANNEL
ENHANCEMENT MODE
HIGH VOLTAGE
POWER MOSFETS**

V_{DSS} **-100V**
 $I_{D(cont)}$ **-4.0A**
 $R_{DS(on)}$ **0.60Ω**

FEATURES

- HERMETICALLY SEALED TO-39 METAL PACKAGE
- SIMPLE DRIVE REQUIREMENTS
- LIGHTWEIGHT
- SCREENING OPTIONS AVAILABLE

TO-39

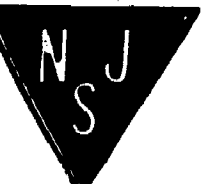
PIN 1 – Source PIN 2 – Gate PIN 3 – Drain

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	±20V
I_D	Continuous Drain Current ($V_{GS} = 0, T_{case} = 25^{\circ}C$)	-4.0A
I_D	Continuous Drain Current ($V_{GS} = 0, T_{case} = 100^{\circ}C$)	-2.6A
I_{DM}	Pulsed Drain Current ¹	-16A
P_D	Power Dissipation @ $T_{case} = 25^{\circ}C$	20 W
	Linear Derating Factor	0.16 W/°C
T_J, T_{stg}	Operating and Storage Temperature Range	-55 to 150°C
T_L	Package Mounting Surface Temperature (for 5 sec)	300°C
$R_{\theta JC}$	Thermal Resistance Junction to Case	6.25°C/W


Notes

- 1) Repetitive Rating – Pulse width limited by maximum junction temperature.



2N6845 IRFF9120

ELECTRICAL CHARACTERISTICS (T_{amb} = 25°C unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS					
BV _{DSS}	Drain – Source Breakdown Voltage	V _{GS} = 0	I _D = - 1mA	- 100	V
ΔBV _{DSS}	Temperature Coefficient of Breakdown Voltage	Reference to 25°C		- 0.10	V/°C
ΔT _J		I _D = - 1mA			
R _{DS(on)}	Static Drain – Source On–State Resistance ¹	V _{GS} = - 10V	I _D = - 2.6A		0.60
		V _{GS} = - 10V	I _D = - 4.0A		0.69
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS}	I _D = -250μA	- 2	- 4
g _{fs}	Forward Transconductance ¹	V _{DS} > -15V	I _D = -2.6A	1.25	S
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} = - 80V	V _{GS} = 0		-25
			T _J = 125°C		-250
I _{GSS}	Forward Gate – Source Leakage	V _{GS} = 20V			100
I _{GSS}	Reverse Gate – Source Leakage	V _{GS} = -20V			-100
DYNAMIC CHARACTERISTICS					
C _{iss}	Input Capacitance	V _{GS} = 0			380
C _{oss}	Output Capacitance	V _{DS} = - 25V			170
C _{rss}	Reverse Transfer Capacitance	f = 1MHz			45
Q _g	Total Gate Charge	V _{GS} = -10V	I _D = -4.0A	4.3	16.3
Q _{gs}	Gate – Source Charge	V _{DS} = -50V		1.3	4.7
Q _{gd}	Gate – Drain ("Miller") Charge			1.0	9.0
t _{d(on)}	Turn–On Delay Time	V _{DD} = -50V			60
t _r	Rise Time	I _D = - 4.0A			100
t _{d(off)}	Turn–Off Delay Time	R _G = 7.5Ω			50
t _f	Fall Time				70
SOURCE – DRAIN DIODE CHARACTERISTICS					
I _S	Continuous Source Current	MOSFET symbol showing the integral reverse p-n junction diode 			- 4.0
I _{SM}	Pulse Source Current				- 16
V _{SD}	Diode Forward Voltage ¹	I _S = - 4.0A	T _J = 25°C		- 4.8
		V _{GS} = 0V			
t _{rr}	Reverse Recovery Time ¹	I _F = -4.0A	T _J = 25°C		200
Q _{rr}	Reverse Recovery Charge ¹	d ₁ / d _t ≤ -100A/μs	V _{DD} ≤ -50V		3.1
t _{on}	Forward Turn–On Time				Negligible

Notes

1) Pulse Test: Pulse Width ≤ 300ms, δ ≤ 2%